

GENERAL PURPOSE AMPLIFIER

Typical Applications

- Broadband, Low-Noise Gain Blocks
- IF or RF Buffer Amplifiers
- Driver Stage for Power Amplifiers
- Final PA for Low-Power Applications
- High Reliability Applications
- Broadband Test Equipment

Product Description

The RF2044 is a general purpose, low-cost RF amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as an easily-cascadable 50Ω gain block. Applications include IF and RF amplification in wireless voice and data communication products operating in frequency bands up to 6000MHz. The device is self-contained with 50Ω input and output impedances and requires only two external DC biasing elements to operate as specified. With a goal of enhanced reliability, the extremely small Micro-X ceramic package offers significantly lower thermal resistance than similar size plastic packages.

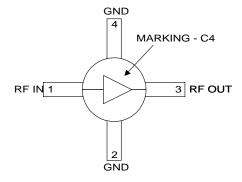
Optimum Technology Matching® Applied

▼ GaAs HBT

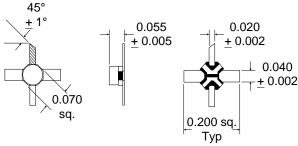
GaAs MESFET

Si Bi-CMOS ☐ SiGe HBT ☐ Si CMOS

Si BJT



Functional Block Diagram



- NOTES:
- 1. Shaded lead is pin 1.
- 2. Darkened areas are metallization.

Package Style: Micro-X Ceramic

Features

- DC to >6000MHz Operation
- Internally matched Input and Output
- 20dB Small Signal Gain
- 4.0dB Noise Figure
- 50mW Linear Output Power
- Single Positive Power Supply

Ordering Information

RF2044 General Purpose Amplifier RF204X PCBA Fully Assembled Evaluation Board

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Absolute Maximum Ratings

Parameter	Rating	Unit
Input RF Power	+13	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-60 to +150	°C



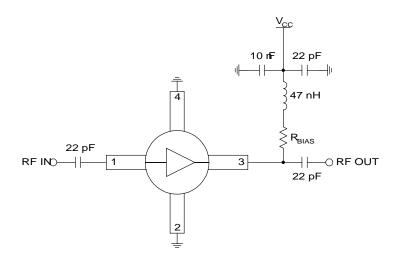
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Parameter	Specification		Unit	Condition		
Farameter	Min.	Тур.	Max.	Unit	Condition	
Overall					T=25 °C, I _{CC} =65mA	
Frequency Range		DC to >6000		MHz		
3dB Bandwidth		3		GHz		
Gain		20.4		dB	Freq=100MHz	
	19.3	20.3	21.3	dB	Freq=850MHz	
	16.5	19.0		dB	Freq=2000MHz	
		17.5		dB	Freq=3000MHz	
		16.6			Freq=4000MHz	
		14.3			Freq=6000MHz	
Gain Flatness		±0.7		dB	100MHz to 2000MHz	
Noise Figure		4.1		dB	Freq=1000MHz	
Input VSWR		<1.4:1			In a 50Ω system, DC to 5000MHz	
Outroot MOM/D		<1.7:1			In a 50Ω system, 5000 MHz to 6000 MHz	
Output VSWR		<1.2:1 <1.8:1			In a 50Ω system, DC to 3000MHz	
Output IB	+30.0	+33.5		dBm	In a 50Ω system, 3000MHz to 6000MHz Freq=1000MHz	
Output IP ₃	+30.0				· ·	
Output P _{1dB}		+18.5		dBm	Freq=1000MHz	
Reverse Isolation		22.3		dB	Freq=1000MHz	
Thermal					I _{CC} =65mA, P _{DISS} =300mW	
Theta _{JC}		188		°C/W		
Maximum Measured Junction		143		°C	T _{AMB} =+85°C	
Temperature at DC Bias Con- ditions						
Mean Time Between Failures		4.0.403		years	T _{AMB} =+85°C	
Weart Time Detween Fandres		1.3x10 ³		,		
		3.1x10 ⁵		years	T _{AMB} =+25°C	
		1.6x10 ⁹		years	T _{AMB} =-40°C	
Power Supply					With 22Ω bias resistor	
Device Operating Voltage	4.3	4.8	5.3	V	At pin 3 with I _{CC} =65mA	
Operating Current	60	65	80	mA		

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Pin	Function	Description	Interface Schematic
1	RF IN	RF input pin. This pin is NOT internally DC blocked. A DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	
2	GND	Ground connection. Keep traces physically short and connect immediately to ground plane for best performance.	
3	RF OUT	RF output and bias pin. Biasing is accomplished with an external series resistor and choke inductor to V_{CC} . The resistor is selected to set the DC current into this pin to a desired level. The resistor value is determined by the following equation: $R = \frac{(V_{SUPPLY} - V_{DEVICE})}{I_{CC}}$ Care should also be taken in the resistor selection to ensure that the current into the part never exceeds 90 mA over the planned operating temperature . This means that a resistor between the supply and this pin is always required, even if a supply near 4.9V is available, to provide DC feedback to prevent thermal runaway. Because DC is present on this pin, a DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF INO
4	GND	Same as pin 2.	

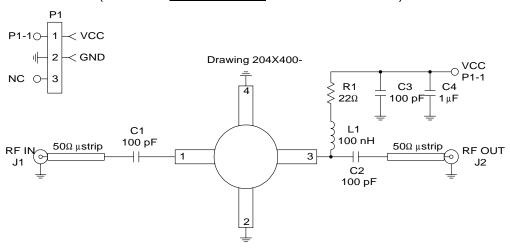
Application Schematic



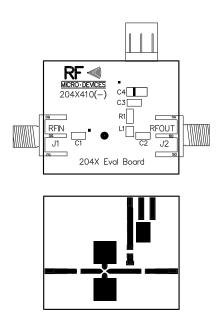
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Evaluation Board Schematic

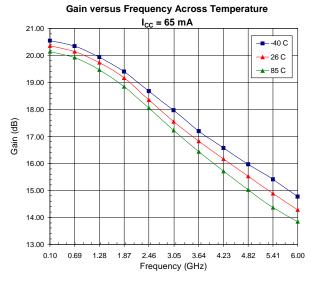
(Download Bill of Materials from www.rfmd.com.)

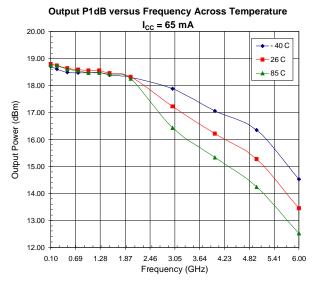


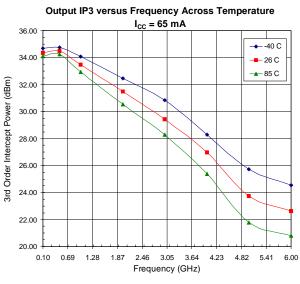
Evaluation Board Layout Board Size 1.195" x 1.000"

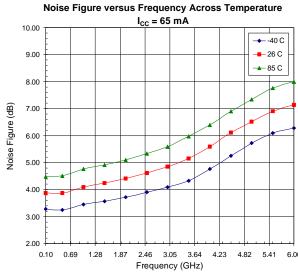


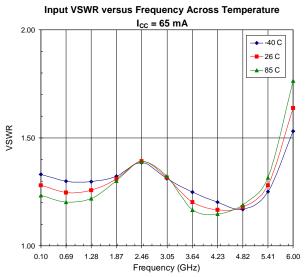
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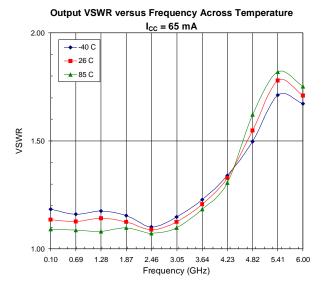






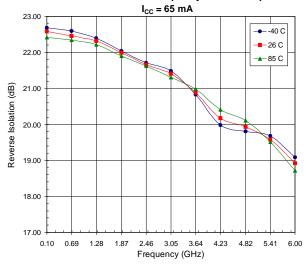




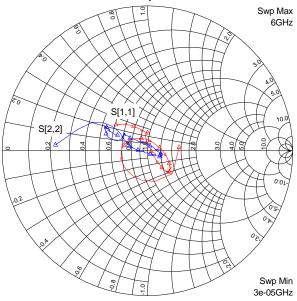


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Reverse Isolation versus Frequency Across Temperature



50 Ohm, 65 mA



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